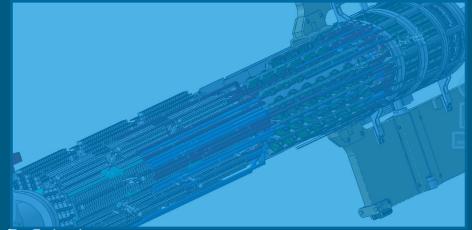




Micro Vertex Detector of PANDA Mechanics updates

MVD Mechanics GSI 10.06.2014



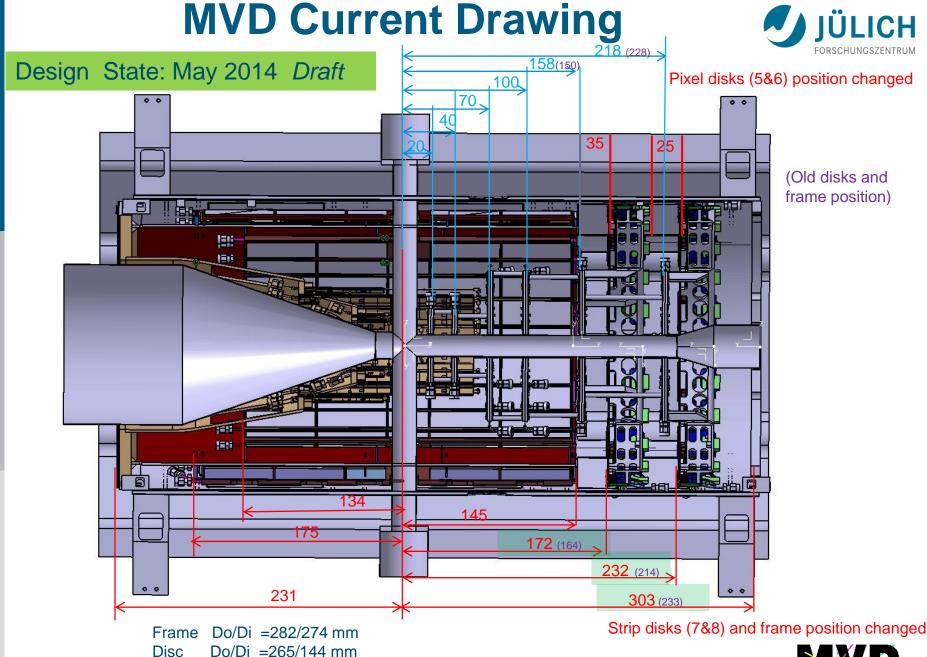
ZEA 1: V. Fracassi, D. Grunwald, E. Rosenthal, R. Schmitz

Content



- MVD Mechanics updates
 - Frame geometry
 - Adaptation of strip and pixel discs.
 - Manifold position
- Manufacturing
- Thermal conductivity experiments





Do/Di =259/259 mm

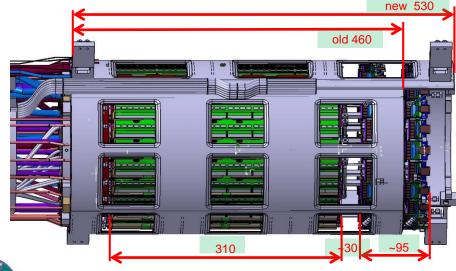
Barrel

MVD new frame design



Longer structure

The frame has to be extended from 460 mm to 530 mm beam downward.

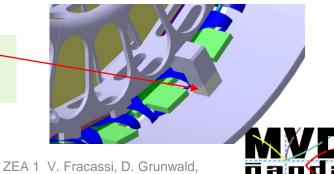


Enlarged windows

The frame windows was adapted according the requirements for cable and pipe devices.

In addition, (if its necessary) the discs cutouts on the top and on the bottom from the frame have to be done in particular for pipe throughout on the vertical axis.

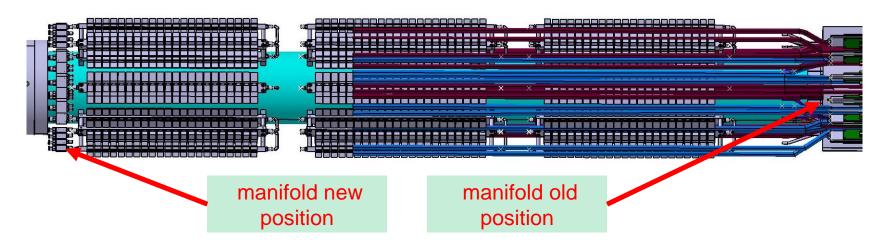
Two connection points /half disk



Manifold position



Design State: May 2014 Draft



The number of cables is still a great space problem. A final solution could not be found. However, it will be required that the manifold must be moved from its current position between DC-DC converter and the GBT to the outer position before the DC-DC converter outside the magnet.

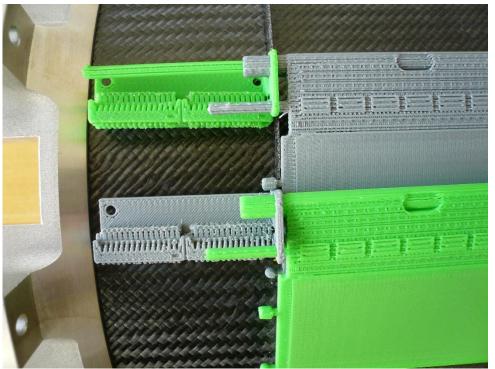
An option to create more space for passage of the cables and pipes is to omit the horizontal connector bridge of the GBT and to enable the corresponding connections of the signal cable by prolonging the GBT.

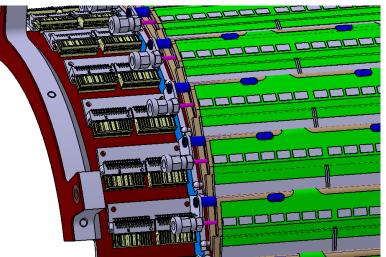


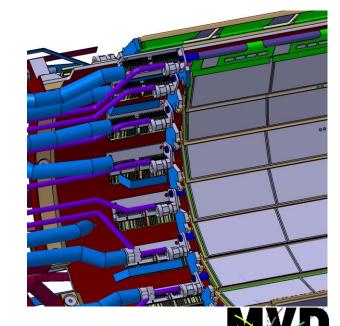
Cable connector



First proposal for a 60-pin cable connector developed from ZEA 2



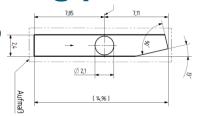






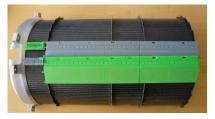
Investigation of manufacturing process

- Test for the processing of carbon foam (Poco HTC) (~2,5*310 mm)
 - Milling, grinding and eroding wire





Components for the ½ 3D model



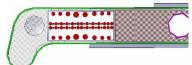






- New Stave Prototype
 - One tube, two tube (short version ~200 mm di=4mm)
 - canal version (~2,5*7mm) (is ongoing by IKV Aachen)
- Test structure for ¼ Strip Disc (is ongoing by IKV Aachen)





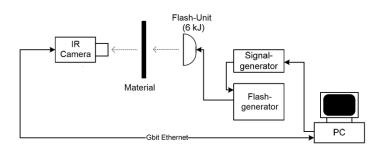




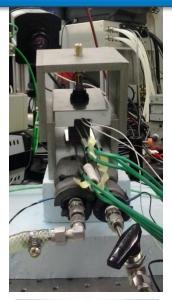
Thermal conductivity investigations



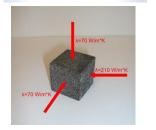
Fast quality check of the thermal conductivity of materials with unidirectional heat conduction

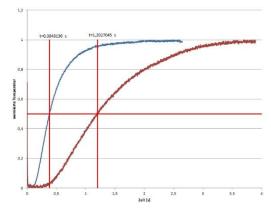


<u>Material</u>	<u>Direction</u>	Thermal conductivity
CFK-Prepack	out of plane	0,3 W/m*K
CFK-Prepacks with RohaCell51 in between	in plane	1,6 W/m*K
	out of plane	0,1 W/m*K
HTC-PocoFoam	in plane	70 W/m*K
	out of plane	210 W/m*K











Outlook



- Design optimization, (Support and positioning system)
- ½ 3 D Model
- Manufacture implementation
- Thermal investigation
- Thermal Hydraulics tests
- FEM Validation
- Cable Routing

Thank you for your attention

